

(12) **United States Patent**  
**Todt et al.**

(10) **Patent No.:** **US 11,824,322 B2**  
(45) **Date of Patent:** **Nov. 21, 2023**

(54) **LASER DEVICE WITH NON-ABSORBING MIRROR, AND METHOD**

USPC ..... 372/44.01  
See application file for complete search history.

(71) Applicant: **II-VI Delaware, Inc.**, Wilmington, DE (US)

(56) **References Cited**

(72) Inventors: **René Todt**, Kriens (CH); **Markus Rösch**, Basel (CH); **Evgeny Zibik**, Zurich (CH); **Susanne Pawlik**, Zurich (CH); **Gustavo F. Villares**, Zurich (CH)

U.S. PATENT DOCUMENTS

10,418,781 B1 9/2019 Jakubowicz  
10,515,332 B2 12/2019 Bielefeldt et al.  
2002/0015428 A1\* 2/2002 Fukunaga ..... H01S 5/164  
372/46.01  
2002/0051477 A1\* 5/2002 Fukunaga ..... H01S 5/2231  
372/46.01

(73) Assignee: **II-VI DELAWARE, INC.**, Wilmington, DE (US)

\* cited by examiner

(\* ) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 320 days.

*Primary Examiner* — Tuan N Nguyen

(74) *Attorney, Agent, or Firm* — Blank Rome LLP

(21) Appl. No.: **17/249,916**

(57) **ABSTRACT**

(22) Filed: **Mar. 18, 2021**

A laser device with one or more active regions, such as quantum wells, gain/lighting media, or other devices, and one or more non-absorbing regions, may be formed by a first growth run (growing a first semiconductor layer), then performing selective, shallow-depth etching, and then a second growth run (growing a second semiconductor layer). The laser device may include a first portion, one or more active regions located on the first portion, and a second portion located on the active region(s). A third portion may be located on one or more ends of the first portion and on the second portion. The third portion may be formed during the second growth run, after the etching step. The non-absorbing region(s) may be formed by the third portion and the end(s) of the first portion. If desired, the non-absorbing region(s) may be produced without annealing or locally-induced quantum well intermixing.

(65) **Prior Publication Data**

US 2022/0263285 A1 Aug. 18, 2022

**Related U.S. Application Data**

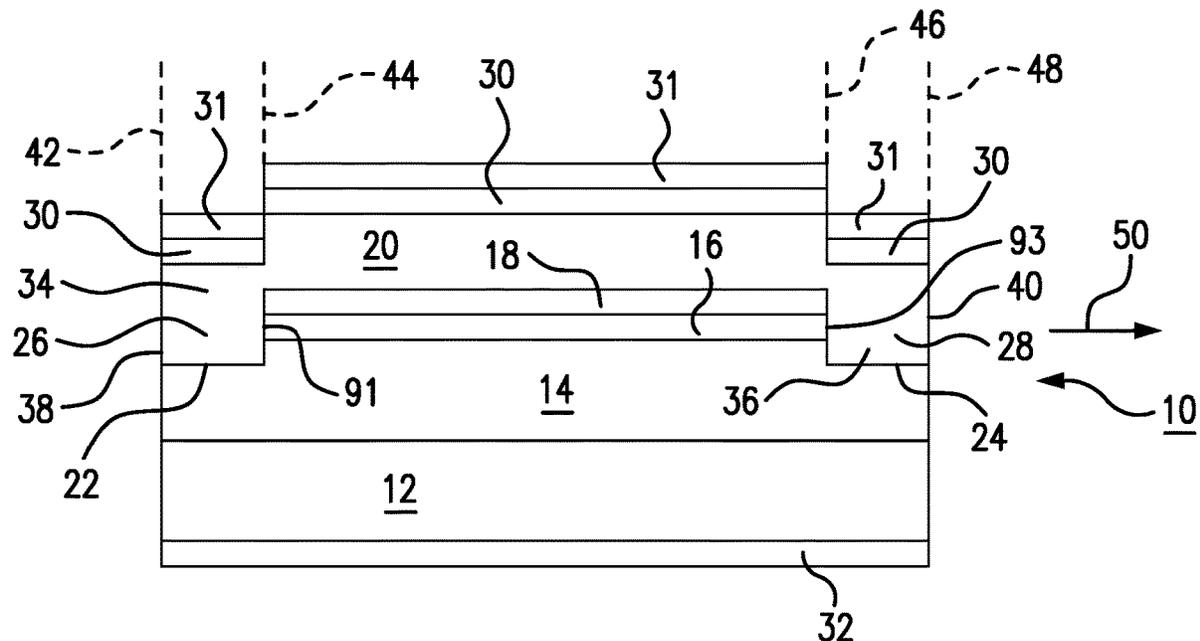
(60) Provisional application No. 63/200,122, filed on Feb. 16, 2021.

(51) **Int. Cl.**  
**H01S 5/02** (2006.01)

(52) **U.S. Cl.**  
CPC ..... **H01S 5/0217** (2013.01); **H01S 2304/04** (2013.01)

(58) **Field of Classification Search**  
CPC .... H01S 5/2086; H01S 5/0217; H01S 5/1039; H01S 2304/04

**19 Claims, 1 Drawing Sheet**





## LASER DEVICE WITH NON-ABSORBING MIRROR, AND METHOD

Applicant claims the benefit of U.S. Provisional Patent Application No. 63/200,122, filed Feb. 16, 2021, under 35 U.S.C. § 119(e). The entire disclosure of U.S. Provisional Patent Application No. 63/200,122 is incorporated herein by reference.

### BACKGROUND

The present disclosure relates to laser devices, including, but not limited to, high-power semiconductor laser diodes, and methods of making laser devices. Some laser devices have facets and mirror surfaces which are susceptible to power degradation and catastrophic optical damage (COD). Methods of improving the facet/mirror surface stability of laser diodes are described in U.S. Pat. No. 10,418,781 (Jakubowicz) and U.S. Pat. No. 10,515,332 (Jakubowicz et al.).

### SUMMARY

The present disclosure relates to a method of making a laser device, where the method includes performing first and second growth runs, and performing an etching step after the first growth run and before the second growth run.

According to one aspect of the present disclosure, the laser device includes first, second and third portions, and one or more active regions. The first and second portions and the active regions are formed during the first growth run, while the third portion is formed during the second growth run. According to this aspect of the present disclosure, the first portion includes semiconductor material, the one or more active regions are located on the first portion, the second portion is located on the one or more active regions, and include semiconductor material, and the third portion is located on one or more end portions of the first portion and on the second portion, and includes semiconductor material. The one or more active regions may be, for example, quantum wells, quantum dots, quantum dashes, quantum wires or double heterojunction. According to another aspect of the present disclosure, one or more non-absorbing regions are formed from the third portion.

The present disclosure also relates to a method of making an edge-emitting laser device, including: (1) performing a first growth run, including epitaxially growing first, second, and third preform layers on a substrate; (2) removing parts of the second and third preform layers by etching the second and third preform layers to form one or more etched regions, and thereby defining one or more ends of one or more active regions, such as quantum wells, and, if desired, leaving a layer of semiconductor material on the one or more active regions; and (3) performing a second growth run, including causing epitaxial growth in the etched region(s), to form one or more non-absorbing regions, and on the layer of semiconductor material. The step of leaving the layer of semiconductor material on the one or more active regions may be employed according to one aspect of the present disclosure, but is not necessarily required. According to one aspect of the present disclosure, the epitaxial growths in the etched region and on the layer of semiconductor material occur simultaneously.

According to another aspect of the present disclosure, a method of making an edge-emitting laser device may include three main steps, performed in sequence, as follows: growing a first semiconductor layer; selectively etching

material grown during the growing of the first semiconductor layer; and growing a second semiconductor layer. As explained in more detail below, the first growing step may include depositing a layer of n-type semiconductor material on a substrate, subsequently depositing a preform layer on the n-type semiconductor material, and subsequently depositing a first layer of p-type semiconductor material on the preform layer. The etching may include removing ends of the first layer of p-type semiconductor material and ends of the preform layer, to thereby form etched regions, and to define the ends of one or more active regions, such as quantum wells, where the active regions are located between the etched regions. The second growing step may include depositing a second layer of p-type semiconductor material in the etched regions, on etched surfaces of the n-type semiconductor material, and on the first layer of p-type semiconductor material, to thereby form non-absorbing regions at opposite ends of the active region(s), and the second layer of p-type semiconductor material may be deposited simultaneously in the etched regions and on the first layer of p-type semiconductor material.

### BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a side view of a laser device constructed in accordance with the present disclosure;

FIG. 2 is a side view of a preform for the laser device of FIG. 1, at a preliminary stage of a manufacturing process; and

FIG. 3 is a side view of a second preform for the laser device of FIG. 1, at a subsequent stage of the manufacturing process.

Throughout the drawings, like elements are designated by like reference numerals and other characters. The drawings show non-limiting examples for purposes of illustration and explanation of the present disclosure, and are not drawn to scale.

### DETAILED DESCRIPTION

FIG. 1 shows an example of an InGaAs/AlGaAs-based quantum-well edge-emitting laser device **10** constructed in accordance with the present disclosure. The device **10**, which may be in the form of a chip or bar, has a substrate **12**, and an n-side portion **14** (an example of a first portion, and of a first-side portion) formed of n-type semiconductor material, and located on the substrate **12**. The device **10** also has one or more quantum wells (examples of active regions in accordance with the present disclosure) **16** located on the n-side portion **14**, and a first p-side portion **18** (an example of a second portion, and of a first second-side portion) formed of p-type semiconductor material, and located on the one or more quantum wells **16**. A second p-side portion **20** (an example of a third portion, and of a second second-side portion) is formed of p-type semiconductor material, and is located on first and second etched surfaces **22**, **24** of the n-side portion **14**, and on the first p-side portion **18**. First and second non-absorbing regions **26**, **28** are located at first and second ends of the device **10**, for forming mirrors at the first and second ends of the device **10**. The laser device **10** also may have a waveguide ridge **30**, and an ohmic contact **31** located on the waveguide ridge **30**. The substrate **12** is located on a second ohmic contact **32**. As illustrated in FIG. 1, most or all of the laser device **10** is operatively located between the two ohmic contacts **31**, **32**.

First and second end portions **34**, **36** of the second p-side portion **20** are located within, and form parts of, the non-

absorbing regions **26, 28**. The second p-side portion **20** and the n-side portion **14** define facets **38, 40** at opposite ends of the non-absorbing regions **26, 28**. The first and second regions **26, 28** are located between first and second planes **42, 44** and third and fourth planes **46, 48**, respectively. The regions **26, 28** are not located between the second and third planes **44, 46**. The facets **38, 40** may be co-planar with the first and fourth planes **42, 48**. The one or more quantum wells **16**, and the first p-side portion **18** are located entirely between the second and third planes **44, 46**, and are not located between the first and second planes **42, 44**, or between the third and fourth planes **46, 48**. In the illustrated configuration, the waveguide ridge **30** and the first ohmic contact **31** extend from the first plane **42** to the fourth plane **48**. However, if desired, the waveguide ridge **30** and the first ohmic contact **31** may be located entirely between the second and third planes **44, 46**, and not between the first and second planes **42, 44**, or between the third and fourth planes **46, 48**. The first and fourth planes **42, 48** are perpendicular to a direction of laser emission **50**. The second and third planes **44** and **46** may be perpendicular to the direction of laser emission **50**.

The n-side portion **14**, the one or more quantum wells **16**, and the first and second p-side portions **18, 20** have vertically built-up graded and/or layered structures (not shown in detail in the drawings) that may include layers of AlGaAs, GaAs, and other materials, including other semiconductor materials, some of which may be doped or undoped. The graded and/or layered structures are epitaxially deposited, during at least a step of growing a first semiconductor layer and a separate step of growing a second semiconductor layer (also referred to herein as two separate growth runs), on the substrate **12**. The present disclosure is not limited, however, to the structure and composition of the illustrated device **10**. Other material combinations may be employed in accordance with the present disclosure. In the illustrated configuration, the substrate **12** may include GaAs.

According to one aspect of the present disclosure, a method of manufacturing the laser device **10** has at least three steps, as follows: First, preform layers **70, 72, 74** (FIG. 2) for forming the n-side portion **14**, the one or more quantum wells **16**, and the first p-side portion **18** are epitaxially deposited on the substrate **12**. The preform layers **70, 72, 74** are part of the preform illustrated in FIG. 2. The preform layers **70, 72, 74** are modified during subsequent steps of the manufacturing process to become elements **14, 16, 18** of the finished product **10**. In particular, a lithography and etching process may be used to remove end portions **80, 82, 84, 86, 88, 90** of the preform layers **70, 72, 74**, to thereby form etched regions at opposite ends of the device **10**. Then, the second p-side portion **20** (FIG. 3) is epitaxially deposited on the n-side portion **14** and the first p-side portion **18**. The end parts **92, 94** of the second p-side portion **20**, which are located on the n-side portion **14**, and the center part **96** of the second p-side portion **20**, which is located on the first p-side portion **18**, are epitaxially deposited simultaneously; that is, the three parts **92, 94, 96** are epitaxially deposited together at the same time. Then the first ohmic contact **31** is formed on the ridge **30**.

The device **10** may be formed by performing two growths, separated by a lithography and etching step. The result of the first growth run is illustrated in FIG. 2. During the first growth run, the n-side portion preform layer **70** is epitaxially grown on the substrate **12**, and then the one or more quantum wells preform layer **72** is epitaxially grown on the n-side portion preform layer **70**, and then the first p-side portion preform layer **74** is epitaxially grown on the one or more

quantum wells preform layer **72**. The three sequentially deposited preform layers **70, 72, 74**, all of which may be deposited during the first growth run, extend continuously in the direction of laser emission **50** from the first plane **42** to the fourth plane **48**. The vertical order and composition of the material layers (not illustrated) within the three preform layers **70, 72, 74** are the same as those within the n-side portion **14** (FIG. 1), the one or more quantum wells **16**, and the first p-side portion **18**, in the finished laser device **10**, at least between the second and third planes **44, 46**.

The thickness  $t_1$  of the third preform layer **74**, which is used to form the first p-side portion **18**, measured in the growth direction **98**, may be, for example, hundreds of nanometers, or not more than a few tens of nanometers, or not more than thirty nanometers. The present disclosure is not limited to the details of the configurations described herein. The illustrated configurations are non-limiting examples in accordance with the present disclosure. After a lithography and etching step (described below), the first p-side portion **18** has essentially the same thickness  $t_1$  as that of the third preform layer **74**. If desired, the third preform layer **74** may be capped by a thin layer **100** of GaAs, GaAsP, InGaP, or another suitable material to minimize oxidation of the surface of the first p-side portion **18** during subsequent processing. The thickness  $t_2$  of the cap layer **100**, in the growth direction **98**, may be, for example, tens of nanometers, or ten nanometers, or a few nanometers. As noted above, the present disclosure is not limited to the details of the configurations described herein. The illustrated configurations are non-limiting examples in accordance with the present disclosure. The growth direction **98** is perpendicular to the direction of laser emission **50**.

The lithography and etching process includes placing a suitable etchant barrier **102** (FIG. 2) over part of the cap layer **100**, and using a suitable etchant **104** to physically etch away, and thereby remove, end portions of the cap layer **100**, and the end portions **80, 82, 84, 86, 88, 90** of the three preform layers **70, 72, 74**, including a small amount of the first preform layer **70** to define the upwardly facing etched surfaces **22, 24** of the n-side portion **14**. The lithography and etching process ensures that no part of the one or more quantum wells **16** or the first p-side portion **18** is located between the first and second planes **42, 44** or between the third and fourth planes **46, 48**, while permitting the one or more quantum wells **16** and the first p-side portion **18** to extend continuously from the second plane **44** to the third plane **46**. The lithography and etching process causes the one or more quantum wells **16** to have etched ends **91, 93** at opposite ends of the device **10**.

The etching depth target, where the etched surfaces **22, 24** are located, may be a few nanometers beneath the plane containing the lower surface of the one or more quantum wells **16**, to ensure complete etching away of the end portions **84, 86** of the second preform layer **72**. In order to avoid surface oxidation and contamination, the layer of the n-side portion **14** in which the etching is stopped should have low aluminum content, or be aluminum free. The etching of the three preform layers **70, 72, 74** may be either wet etching or dry etching. After the etching is completed, the lithography barrier (mask) **102** may be stripped away (that is, removed).

Then the remaining part of the cap layer **100** may be removed under controlled atmosphere or vacuum, to avoid oxidation. The removal of the remaining part of the cap layer **100** may be performed by a baking procedure, or in-situ etching within a metalorganic vapor-phase epitaxy (MOVPE) process. Then the exposed surface of the first

p-side portion **18** may be cleaned to reduce the level of surface contamination, and the cleaning step may be immediately followed by the second growth, which includes epitaxial growth of the second p-side portion **20**. The cleaning step may include baking, etching, or a combination of baking and etching. A feature of the illustrated method is that the second growth is applied across the entire device **10**—no selective growth is required, since the first growth is interrupted by the lithography and etching process.

According to a preferred aspect of the present disclosure, the lithography and etching process may be optimized to minimize any impact on the interfaces between non-etched and etched parts, which are coplanar with the second and third planes **44**, **46**. Too large of a step at the interfaces, in the growth direction **98**, could result in a strong mode mismatch across the interfaces in the direction of laser emission **50**, which could result in a corrugated vertical farfield laser pattern, and scattering of light into the substrate **12**, increasing optical loss of the laser device. On the other hand, according to one example of the present disclosure, the growth interface from the first growth to the second growth should not be too close to the one or more quantum wells **16**. According to another aspect of the present disclosure, providing the first p-side portion **18** with a thickness  $t_1$ , in the growth direction **98**, in the range of from 30 nm to 200 nm should be sufficient to reduce the overlap of this interface with the optical mode to meet reliability targets in all or most telecommunication systems.

Thus, according to the present disclosure, the device **10** may be formed by epitaxial growth performed in two separate growth runs (that is, in a step of growing a first semiconductor layer and a separate step of growing a second semiconductor layer), instead of in a single growth run. In the illustrated embodiment, the epitaxial growth runs are separated from each other in time by at least the step of etching and removing the end portions **84**, **86** of the second preform layer **72**. The first growth step defines the bottom half of the laser structure, which includes n-waveguide material, an active region with single or multiple active regions, such as quantum wells, and a small part of the p-type waveguide. The latter layer may be formed to a thickness  $t_1$  of 0 nm to 200 nm, or more preferably from 30 nm to 200 nm, above the last-grown quantum well. Moreover, to reduce risk of oxidation of material within the one or more quantum wells **16**, which may include AlGaAs, the cap layer **100** may be formed of a suitable material such as GaAs, GaAsP, or InGaP.

Between the first and second growth runs (that is, between the step of growing the first semiconductor layer and the separate step of growing the second semiconductor layer), shallow etching of the three preform layers **70**, **72**, **74** is performed to remove portions **84**, **86** of the one or more quantum wells preform layer **72**, and the etch is extended to a desired depth  $d_1$ , for example a depth of from 0 nm to 50 nm, below the lowest surface of the one or more quantum wells **16** in the areas where the edge-emitting laser facets **38**, **40** will be defined. The length  $l_1$  of each such area, in the direction of light emission **50**, may be in the range of from  $<1 \mu\text{m}$  to  $100 \mu\text{m}$ . If desired, the lengths  $l_1$  of the two areas may be different from each other. The present disclosure is not limited to the details of the configurations described herein. The illustrated configurations are non-limiting examples in accordance with the present disclosure.

If desired, a plurality of the devices **10** may be formed within a single wafer. The devices **10** may be separated from each other by cleaving or etching. The etched features may be arranged periodically on the wafer with a period equal to

the laser cavity length in the direction of laser transmission **50**, and equal to the laser pitch in a direction perpendicular to the direction of laser emission. However, if lasers with different pitch and cavity lengths are produced, the etching arrangement within the wafer may be quasi-periodical. During the etching step, alignment marks may be defined on the surface of the wafer to allow for consecutive laser fabrication processing. The wafer surface should be deoxidized/cleaned before performance of overgrowth steps.

The facet stability of a high-power edge-emitting diode laser may be a critical parameter for achieving high reliability. If the cleaved facets of the device are not protected, catastrophic failure at the front facet of the laser may occur even within the first few hours of operation. The present disclosure achieves the desired stabilization without necessarily requiring passivation of the facet surfaces. However, if desired, facet passivation may be used in combination with the approaches described above in order to avoid the formation of deep surface states/centers, which could still absorb light.

According to the present disclosure, the ends of the active region(s), such as quantum well(s), are removed close to the laser facets (that is, the one or more active regions do not extend the entire length of the device **10**), and the removed material is replaced by non-absorbing higher-bandgap material to form the non-absorbing regions **26**, **28**. Thus, the present disclosure relates to a method of forming one or more non-absorbing regions without inducing quantum-well intermixing (QWI) close to a laser facet. It is advantageous to avoid high-temperature annealing, which could be used to achieve quantum-well intermixing, because such annealing may have an undesired effect on the quantum well(s). The undesired effect may be especially undesirable if it occurs between planes **44** and **46**. In general, for regions that are not between planes **44** and **46**, intermixing may be desirable.

According to a preferred aspect of the present disclosure, the device **10** may be manufactured without having to perform an etching step after the second p-side portion **20** is completely or even substantially formed. Therefore, according to the present disclosure, it is not necessary to complete, or even substantially complete, the epitaxial growth of a complete laser device, then etch away a portion of the device, and then perform a selective re-growth of wide-bandgap material. A process involving such deep etching (e.g., deeper than  $1 \mu\text{m}$ ) could be technologically difficult and expensive to perform, especially when the length  $l_1$  of the etched region is relatively short. In the illustrated configuration, the total depth of the etched regions may be, for example, less than 250 nm.

Thus, the present disclosure avoids having to perform selective growth in a deep trench (e.g., deeper than  $1 \mu\text{m}$ ) and facilitates the formation of non-absorbing regions **26**, **28** that are relatively short (that is, not long in the laser emission direction **50**) so as to avoid losing gain material. The areas where the active regions, such as quantum wells, are removed form regions where light is not absorbed, thus inhibiting a root cause for catastrophic mirror damage. The lengths  $l_1$  of the non-absorbing regions, in the direction of laser emission **50**, may be the same, or the front and back regions may have different lengths, especially depending on optical power distribution within the optical cavity of the laser device.

The device **10** illustrated in FIG. **1** has two non-absorbing regions **26**, **28** both of which are formed by the process illustrated in FIGS. **2** and **3**. The present disclosure is not limited, however, to the illustrated configuration. The present disclosure also relates to a device which has (A) one

region **28** at an outgoing end, which is formed by a first growth, followed by shallow etching, and then a second growth, and (B) some other suitable structure at the other end of the device.

There are also other advantages of the shallow-etching process compared to a deep-etching process, as follows: In order to avoid undesired back-reflections at the interface between the laser active region and a non-absorbing region, the effective index of the mode should be closely matched in the non-absorbing regions **26**, **28**. Such matching requires knowledge of the actual index of the lasing mode. Another, separate disadvantage associated with the deep-etching process is that, since the epitaxial growth in a deep trench could start on all surfaces, including side-walls, such deep growth could result in growth defects and/or dislocations.

According to an alternative embodiment of the present disclosure, a refractive index step may be established at the overgrowth interface in order to provide a broadband mirror with well-defined reflectivity to provide the desired feedback into the laser cavity.

A feature of the shallow-etching process described above is that the end parts **92**, **94** of the second p-side portion **20** and the center part **96** of the second p-side portion **20** may be deposited simultaneously. As a result, the vertical layered structures of the end parts **92**, **94** and the center part **96** closely correspond to each other, without any etching-induced break or discontinuity between the vertical layered structures. Structural differences between (A) a device like the device **10** and (B) a device formed with a deeper etch, where the non-absorbing regions are formed by selective deposition after most or all of the p-type vertical structure in the device is deposited, may be detected in various ways.

Among other techniques, a signature of a non-absorbing region formed according to a shallow-etch process may be observed by optical microscopy using a Nomarski prism to enhance height contrasts. Since the area close to the laser facet is relatively thin, a contrast may be observed in the microscope image. Differences may also be observed by using a cross-sectional tunneling electron microscope (TEM) image of the laser ridge **30** close to the laser facets **38**, **40**. A characteristic trace of the growth interface will be visible. This technique would also allow distinguishing the device **10** from one formed by a selective overgrowth process where one would see the material contrast between the non-absorbing region and the main part of the laser device. For broad-area lasers, secondary ion mass spectrometry (SIMS) measurements close to a facet and in the center of the laser device may reveal a characteristic difference in layer structure between (A) a device like the device **10** and (B) a device formed by a deep-etching step and subsequent selective epitaxial deposition.

The method described above is not limited to the described materials, and is not limited to just AlGaAs-based lasers. The method is also applicable to other epitaxial semiconductor lasers, including, but not limited to, AlGaIn-based lasers, and especially for devices in which catastrophic facet damage could occur and facet stability should be preserved.

Further, if desired, a laser device may be constructed as described herein but by employing n-type semiconductor material instead of p-type semiconductor material while employing p-type semiconductor material instead of n-type semiconductor material.

The present disclosure is applicable to a variety of devices, including, but not limited to, narrow-stripe 980 nm pump lasers, broad-area single emitter lasers, bar products,

and short-cavity narrow-stripe lasers, which may be used, for example, in connection with heat-assisted magnetic recording (HAMR) systems. The present disclosure may be applicable in a variety of systems, including, but not limited to, optical-pumping systems in telecommunications equipment, industrial high-power laser diode systems, automotive LIDAR systems, and heat and/or light-assisted magnetic recording systems for use in connection with hard disks.

What have been described above are examples. This disclosure is intended to embrace alterations, modifications, and variations to the subject matter described herein that fall within the scope of this application, including the appended claims. As used herein, the term "includes" means including but not limited to. The term "based on" means based at least in part on. Additionally, where the disclosure or claims recite "a," "an," "a first," or "another" element, or the equivalent thereof, it should be interpreted to include one or more than one such element, neither requiring nor excluding two or more such elements. The order in which steps are recited in the claims is not, by itself, limiting.

What is claimed as new and desired to be protected by Letters Patent of the United States is:

**1.** A method of making an edge-emitting laser device, comprising:

**1.** epitaxially growing first, second, and third preform layers on a substrate;

subsequently, removing parts of the second and third preform layers by etching the second and third preform layers to form an etched region, and thereby forming one or more active regions from the second preform layer, defining an end of the one or more active regions, and leaving a layer of semiconductor material on the one or more active regions; and

subsequently, causing epitaxial growth in the etched region to form a non-absorbing region, and on the layer of semiconductor material, and wherein the epitaxial growths in the etched region and on the layer of semiconductor material occur simultaneously.

**2.** The method of claim **1**, wherein the one or more active regions of the laser device made by the method are located on a first portion, wherein material for the first portion and the one or more active regions is formed during a first growth run; wherein another portion of the laser device, located on an end portion of the first portion, is formed during a second growth run; and wherein the non-absorbing region is formed by the other portion.

**3.** The method of claim **2**, wherein the laser device made by the method includes a second portion located on the one or more active regions, wherein material for the second portion is formed during the first growth run, wherein the other portion is a third portion, wherein the first portion includes n-type semiconductor material, and wherein the second and third portions include p-type semiconductor material.

**4.** The method of claim **3**, wherein the one or more active regions has an etched end, the first portion and the third portion define a facet, and the non-absorbing region is located between the etched end and the facet.

**5.** The method of claim **4**, wherein the laser device made by the method includes a substrate, and wherein the first portion is located on the substrate.

**6.** The method of claim **5**, wherein the laser device made by the method includes first and second ohmic contacts, wherein the substrate is located on the second ohmic contact, and wherein the first portion, the one or more active regions, and the second and third portions are located between the first and second ohmic contacts.

9

7. The method of claim 2, wherein the non-absorbing region of the laser device made by the method includes a first material, the one or more active regions includes a second material, and the first material has a larger band-gap than the second material, such that light generated by the laser device is not absorbed by the region, to thereby avoid catastrophic damage.

8. The method of claim 7, wherein the non-absorbing region has a length in a direction of light emission, and wherein the length of the non-absorbing region is not greater than 500  $\mu\text{m}$ .

9. The method of claim 8, wherein the non-absorbing region is formed at an end of the laser device, wherein the laser device further includes a second non-absorbing region, and wherein the second non-absorbing region is formed during the second growth run.

10. The method of claim 1, wherein the first preform layer is formed of n-type semiconductor material, the third preform layer is formed of a type of semiconductor material, which may be p-type or n-type semiconductor material, and the epitaxial growths in the etched region and on the layer of semiconductor material include deposition of the same type of semiconductor material.

11. The method of claim 10, further comprising locating the first preform layer on a substrate, providing an ohmic contact on a first side of the device and connected to the substrate, and providing an ohmic contact on a second side of the device after causing the epitaxial growth on the layer of semiconductor material.

12. The method of claim 11, further comprising forming a facet from the first preform layer and the epitaxial growth in the etched region.

13. The method of claim 12, further comprising forming a second etched region, and thereby defining a second end of the one or more active regions, and causing epitaxial growth in the second etched region to form a second non-absorbing region.

14. A method of making an edge-emitting laser device, comprising:

growing a first semiconductor layer;  
subsequently, selectively etching material grown during the growing of the first semiconductor layer; and  
subsequently, growing a second semiconductor layer;  
wherein the growing of the first semiconductor layer includes depositing a layer of n-type semiconductor

10

material on a substrate, subsequently depositing a preform layer on the n-type semiconductor material, and subsequently depositing a first layer of p-type semiconductor material on the preform layer;

wherein the etching includes removing ends of the first layer of p-type semiconductor material and ends of the preform layer, without removing all of the first layer of p-type semiconductor material, and without removing all of the preform layer, to thereby form etched regions, and to thereby define one or more active regions between the etched regions; and

wherein the growing of the second semiconductor layer includes depositing a second layer of p-type semiconductor material in the etched regions, on etched surfaces of the layer of n-type semiconductor material, and on the first layer of p-type semiconductor material, to thereby form non-absorbing regions at opposite ends of the one or more active regions, and wherein the second layer of p-type semiconductor material is deposited simultaneously in the etched regions and on the first layer of p-type semiconductor material.

15. The method of claim 14, further comprising providing ohmic contacts on opposite sides of the edge-emitting laser device.

16. The method of claim 15, wherein the growing of the first semiconductor layer includes depositing a cap layer on the first layer of p-type semiconductor material, wherein ends of the cap layer are removed during the etching, and wherein a remaining portion of the cap layer is subsequently removed.

17. The method of claim 16, wherein a lithography mask is used during the etching.

18. The method of claim 17, further comprising forming facets at ends of the laser device, wherein the facets are formed from the layer of n-type semiconductor material and the second layer of p-type semiconductor material.

19. The method of claim 18 wherein the non-absorbing regions include regions where light generated by the laser device is not absorbed, to thereby avoid catastrophic damage, and wherein each one of the non-absorbing regions has a length not greater than 500  $\mu\text{m}$  in a direction of laser emission.

\* \* \* \* \*